

Nov 5th, 2024 (Tue)							
15:30-18:00	Registration (Lobby, 2F)						
Nov 6th, 2024 (Wed)							
Room	Grand Ballroom A+B (400)	Capri (120)	Sicily (100)	Sydney (70)	Venice (32)	Miami (32)	
Topic	Advanced Packaging I	Defect Inspection and Metrology	MEMS/NEMS, Sensors, and Display Packaging Technology	Automotive and Power Electronic Packaging	Materials for Interconnects and Packaging I	Young Scientist I	
Session Chair	Mhin Sungwook	Park Jiyong	Kang Sumin	Kim Dongjin	Ko Yong-Ho	Park Ah-Young	
10:30-10:55	I1-01 Kim Bioh, Yield Engineering Systems, Inc., Korea Innovations in Various Process Technologies for Advanced Packaging	I1-03 Ryu Ill, Seoul National University, Korea Defect-Driven Plasticity in Microelectronics under Thermal Cycles	I1-06 Kang Sumin, Seoul National University of Science and Technology, Korea Advanced Transfer Technologies of Ultrathin Films for Flexible Electronics	I1-08 Kim Yoonjin, Teraon Co., Ltd., Korea Advanced Non-pressure Die Attach Paste of High Thermal Conductivity and Low Modulus for Power Semiconductor Packages	I1-12 Thomas Olivier, IM2NP, France Synchrotron X-ray Light for Understanding Ge-rich Ge-Sb-Te Materials Used as Embedded Phase Change Materials in Automotive Applications (Online)	O1-07 Kim Dong Jun, Korea Advanced Institute of Science and Technology (KAIST), Korea Study on the Intrinsic Thermo-mechanical Properties of TEOS-SiO₂ Thin Films by Thickness through Etching of Naturally Formed Copper Oxide	
10:55-11:20	I1-02 Moon Hyunkyu, Korea Institute of Machinery and Materials (KIMM), Korea 3D Integration of Thin Die on Curved Surfaces for Optical Applications	I1-04 You Joonho, nexensor Inc., Korea The Study of Optical Measurement Technologies for Advanced Packaging and HBM Process	I1-07 Kim Seok, Pohang University of Science and Technology (POSTECH), Korea Transfer Printing for Micro-LED Assembly & Advanced Packaging	I1-09 Yoon Sang Won, Seoul National University, Korea Considerations for Packaging Solutions for Current Automotive Power Modules	I1-13 Han Dongwoo, SK hynix Inc., Korea Material Development Trends for Advanced Packaging	O1-08 Lee Gyeongmin, Hansung University, Korea Automatic ROI Recommender for Saw Singulation: Seamless Adaptation for Various Semiconductor Device	
11:20-11:45	O1-01 Moon Seunghyun, Hanwha NxD Co., Ltd., Korea Irregular Shape SIP Package Manufacturing Process	I1-05 Kim Mujin, DeepSeers, Korea Semiconductor Package Inspection: A Comparative Analysis of Machine Vision Techniques for Defect Detection	O1-04 Shin Jungho, Electronics and Telecommunications Research Institute (ETRI), Korea Simultaneous Transfer and Bonding (SITRAB) Technology for Integrating Micro-LEDs onto Display Backplanes	I1-10 Chen Chuantong, Osaka University, Japan Development of Low Temperature Ag-Si Composite Paste Sintering Material for High-reliability SiC Power Modules (Online)	I1-14 Kang Sung-Gyu, Gyeongsang National University, Korea Strain Rate and Temperature-Dependent Micromechanical Properties of Copper Micropillars Fabricated by Localized Electrodeposition	O1-09 Lee Geunil, Sungkyunkwan University, Korea Digital Signal-based Method for Failure Diagnosis of Interconnects under Use Condition	
11:45-12:10	O1-02 Na Youngeun, Hana Micron, Korea Optimizing Power integrity in 2.xD Packaging for High-Performance Computing	O1-03 Oh Seung Jin, Korea Institute of Machinery and Materials (KIMM), Korea Mechanical Testing for Advanced Semiconductor Process and Equipment	O1-05 Paek Mun Cheol, Y-TECH Co., Ltd., Korea Implementation of a Low Temperature Co-fired Ceramic Package for All Solid-State Hydrogen Sensor Modules	I1-11 Li Mingyu, Harbin Institute of Technology (HIT), Shenzhen, China Focused Electromagnetic Induction Heating Technology and Its Application Exploration	O1-06 Kwon Hyeon Ahn, ExleetEdge, Inc., Korea A Case Study of the EdgeAI^{Stack} for the Health Monitoring of the Solder Joints of Electronic Packages Used in the System of the Railroad Industry	O1-10 Thi Phuong Bui, Korea Institute of Industrial Technology (KITECH), Korea Size Effects of Mono-dispersed Hollow Silica Spheres on Transparency and Superhydrophobicity	
12:10-13:30	Lunch				Special Session 11 (Closed Session)		
Session Chair	Kim Taek-Soo				Han Jinho		
13:30-14:00	Plenary Talk 1 (Grand Ballroom) - Lee Kangwook, SK Hynix Inc., Korea HBM (High Bandwidth Memory) and Advanced Packaging Technology for AI Era				Special Session 12 (Closed Session)		
14:00-14:30	Keynote Talk 1 (Grand Ballroom) - Kristina Kutukova, PVA Technology Hub GmbH, Germany Mechanical Robustness of Chiplets – An X-ray Microscopy Study (Online)				Shim Sang Eun		
14:30-14:40	Break Time				"PIM 2.5D Large-Scale Super-Performance Interposer and 3D Hybrid Bonding Platform for PIM Semiconductor Integrating Processors and High-Bandwidth Memories" Electronics and Telecommunications Research Institute (ETRI)		
Session Chair	Kim Tae-Il						
14:40-15:10	Keynote Talk 2 (Grand Ballroom) - Park Seungbae, State University of New York at Binghamton, USA Reliability Challenges for Heterogeneously Integrated Packages						
15:10-15:40	Keynote Talk 3 (Grand Ballroom) - Katsuaki Sugauma, Osaka University, Japan Interconnection Technology for Advanced and Power Semiconductors				Inha University		
15:40-15:50	Break Time						
Topic	Novel Packaging Technologies	Advanced Packaging II	Thermal Management I	Materials for Interconnects and Packaging II	Special Session 1 (Closed Session)	Special Session 2 (Closed Session)	
Session Chair	Kim Jong-Woong	Joo Jiho	Nam Youngsuk	Kim Hyun-Sik	Kwon Daeil	Lee Hakjun	
15:50-16:15	I1-15 Georg Berger, EV Group, Austria Maskless Exposure Lithography Enables Novel Semiconductor Development in Advanced Packaging	I1-18 Lee Jeong Won, Nepes Corporation, Korea Chip-let Heterogeneous Integration Packaging Based on Fan-out RDL Interposer Technology	I1-21 Kang Joon Sang, Korea Advanced Institute of Science and Technology (KAIST), Korea High Thermal Conductivity Material for Thermal Management in Electronics Packaging	I1-24 Kim Hyun-Sik, University of Seoul, Korea Effect of Y2O3-RE2O3(RE= Nd, Sm, Tb, Dy, Tm)-MgO Additives on Mechanical and Thermal Properties of Silicon Carbide Ceramics	"Reliability and Thermal Management for Advanced Packages I" Sungkyunkwan University	"Micro Semiconductor Socket for Highly Integrated Semiconductor Inspection" Korea Institute of Industrial Technology (KITECH)	
16:15-16:40	I1-16 Jeon Eunsuk, Laserapps Co., Ltd., Korea Novel Singulation of Glass Substrate for Next Generation Advanced Semiconductor Packaging	I1-19 Yeon Hanwool, Gwangju Institute of Science and Technology (GIST), Korea Monomolecular Coating on Copper for Reliable Organic Interposers under Mechanical, Thermal, and Electrical Stress	I1-22 Cho Jungwan, Sungkyunkwan University, Korea Thermal Property Measurements using Thermoreflectance Techniques for Device and Packaging Applications	I1-25 Iwanaga Hiroki, Toshiba Corporation (Visiting Professor of Rikkyo University), Japan Novel Eu(III) Complexes with an Asymmetric Diphosphine Dioxide Ligand and their Potential uses in Micro-LED Displays as Red Phosphors			
16:40-17:05	O1-11 Sung-Bin Kim, AnyCasting Co., Ltd., Korea Electroplating Technology for the Cu-Filling of Via Holes in 4-inch Wafer-Sized Glass Substrate	I1-20 Hwang Kyojin, Samsung Electronics Co., Ltd., Korea New Embedding Capacitor Solutions for Extremely Large FC-BGA Package Platform	I1-23 Jang Hyejin, Seoul National University, Korea Thermal Transport Properties of Electronics Packaging at the Nanoscale	I1-26 Park Hyun, Dong-A University, Korea Microstructure and Elongation of Cu Foil Fabricated through Electrodeposition for Batteries			
17:05-17:30	I1-17 Kim Younghyun, Hanyang University, Korea Next-Gen Innovations: Co-Packaged Optics and Silicon Photonics	O1-12 Kirihata Tomoka, Lintec Corporation, Japan A novel Transfer Bonding Process with Particle Less Tapes for Die to Wafer Integration	Sponsor Night Setting	I1-27 Sangyup Kim, Sogang University, Korea Composite Materials for Managing Thermal Behavior in Semiconductor Testing and Packaging			
17:30-18:00	Break Time						
18:00-20:00	Sponsor Night and Lucky Draw (Sicily)						

Nov 7th, 2024 (Thu.)							
Room	Grand Ballroom A+B (400)	Capri (120)	Sicily (100)	Sydney (70)	Venice (32)	Miami (32)	
Topic	Next-generation Electronic Devices	Packaging Design and Modeling	Flexible, Wearable, and Printed Electronics I	Materials for Interconnects and Packaging III	Special Session 3 (Closed Session)	Special Session 4 (Closed Session)	
Session Chair	Suh Minsuk	Shin Hyunseong	Kim Tae-il	Kim Min-Su	Kwon Daeil	Lee Hakjun	
9:00-9:30							
9:30-9:55	I2-01 Rettenmeier Roland, Evatec AG, Switzerland TGV for HPC	I2-04 Kim Myeong-Woo, Synopsys, Inc., Korea Multiscale Thermal, Mechanical and Performance Analysis for 3DIC with HBM	I2-06 Kim Hyeok, University of Seoul, Korea Organic Packaging for Encapsulated Power-free Flexible Devices	I2-09 Noh Sangkyun, Simmtech Co., Ltd., Korea Prepreg-based FCBGA for Advanced Packaging Substrate	"Reliability and Thermal Management for Advanced Packages II" Sungkyunkwan University	"Die Socket for Stacked Semiconductors and Test Handler Development" Korea Institute of Industrial Technology (KITECH)	
9:55-10:20	I2-02 Kuramochi Satoru, Dai Nippon Printing (DNP) Co., Ltd., Japan RDL on Glass for High Performance Computing Application	I2-05 Kim Rock, Siemens EDA, Korea Innovator3D IC - Siemens EDA's Comprehensive Multiphysics Cockpit for 3D IC Design	I2-07 Jung Yei Hwan, Hanyang University, Korea Curvilinear Electronics based on Shape Deformable Stamp	I2-10 Hiroaki Tatsumi, Osaka University, Japan Cu Ribbon Soldering on Power Module Substrate using Blue Diode Laser			
10:20-10:45	I2-03 Lim Jae-Hong, Gachon University, Korea Optimization of Additive and Current Conditions for Void-Free Filled Through-Glass/AAO Via	O2-01 Hsu Shang-Feng, National Cheng-Kung University, Taiwan Development of an Innovative Process Emulator for Nonlinear-Bifurcated Warpage Prediction in FOWLP with Material Equivalence Approach	I2-08 Xinge Xu, City University of Hong Kong, Hong Kong Engineering of Packing Materials for Permeable Wearable Electronics	O2-02 Lee Byunghoon, Samsung Electronics Co., Ltd., Korea Development of Non Conductive Film (NCF) for Fine Pitch Connector-less Bonding with Low Temperature Solder			
10:45-10:55	Break Time						
10:55-11:10	Sohn Yoonchul Opening Remark - Sayoon Kang / KMEPS (Grand Ballroom)					Special Session 13 (Closed Session)	
11:10-11:40	Plenary Talk 2 (Grand Ballroom) - Ehrenfried Zschech, Brandenburg University of Technology, Germany Combining Acoustic Microscopy and X-Ray Microscopy for Metrology, Inspection and Failure Analysis in Advanced Packaging						
11:40-12:10	Keynote Talk 4 (Grand Ballroom) - Kim Jichul, Samsung Electronics Co., Ltd., Korea Embracing Advanced Packaging for Future AI-Enabled Consumer Electronics					"Core Technologies Development of Polymer Interposer Materials and Processes for 2.xD Advanced Packages" Workshop LG Innotek	
12:10-13:10	Lunch						
13:10-14:00	Ko Yong-Ho, Yoon Sang Won Poster Presentation (Grand Ballroom)						
14:00-14:30	Keynote Talk 5 (Grand Ballroom) - Lim Choon Khoo, ASMP, Singapore Enabling the AI Era						
14:30-15:00	Keynote Talk 6 (Grand Ballroom) - Joo Young-Chang, Seoul National University, Korea Reliability Challenges in Advanced Interconnect and Packaging						
15:00-15:20	Break Time						
Topic	Advanced Packaging III	Reliability of Electronic Devices and Systems	Flexible, Wearable, and Printed Electronics II	ICEP Session	Materials for Interconnects and Packaging IV	Thermal Management II	
Session Chair	Nam Seunghoon	Lee Tae-ik	Jung Yei Hwan	Yasuhiro Morikawa	Kim Young-Cheon	Cho Jungwan	
15:20-15:45	I2-11 Moreau Stephane, CEA, France How did the "Hybrid Bonding" Technology become Reliable?	I2-14 Kang Tae Yeob, The University of Suwon, Korea Non-destructive Assessment of Corrosion in Electronic Packages by Processing S-parameters	I2-16 Kim Tae-Il, Sungkyunkwan University, Korea Package for Advanced Bioelectronics	I2-21 Hanna Taku, ULVAC Inc., Japan Polymer Fine via Formation based upon Plasma Etching Technology for 3D Chiplet Integration	I2-25 Zhang Zheng, Osaka University, Japan Application of Ag Cap for Fine-pitch Cu Pillar Interconnection	I2-26 Moon Seok Hwan, Electronics and Telecommunications Research Institute (ETRI), Korea Overcoming the Limitations of Heat Dissipation Technology due to High Integration and Thickness Reduction in Packaging	
15:45-16:10	I2-12 Park Kyung-Ho, Korea Advanced Nano Fab Center (KANC), Korea The Study of the Chemical Mechanical Polishing (CMP) Parameters for Enhanced 3D Cu Hybrid Bonding	I2-15 Kleyan Armen, Siemens EDA, Armenia Full-chip CPI Assessment for IC Performance and Reliability with Accurate Account of Thermal Effects	I2-17 Song Young Min, Gwangju Institute of Science and Technology (GIST), Korea Bioinspired Advanced Camera Modules for Application-specific Vision Systems	I2-22 Miyoshi Takayuki, Toray Engineering Co., Ltd., Japan Demonstration of Flux-less Bonding with Simplified Equipment Configuration	O2-07 Bae Byeong-Soo, Korea Advanced Institute of Science and Technology (KAIST), Korea Low Dk/Df Siloxane Hybrid Material for Advanced Packaging Substrate	I2-27 Nam Youngsuk, Korea Advanced Institute of Science and Technology (KAIST), Korea High-Efficiency Liquid Cooling for Semiconductor Devices	
16:10-16:35	O2-03 Lim Jae-Sung, Hana Micron, Korea Development and Structural Analysis of 2.xD Advanced Package with a Bridge Die-based Platform	O2-04 Jeong Hakyung, Korea Institute of Machinery and Materials (KIMM), Korea Evaluation of Adhesive Energy in Symmetric and Asymmetric Substrate Bonding for Temporary Bonding and Debonding	I2-18 Kim Sunkook, Sungkyunkwan University, Korea Human Interactive Sensors and Devices	I2-23 Fukushima Takafumi, Tohoku University, Japan 3D-IC and Hybrid Bonding Activity in Tohoku CHIPS	O2-08 Kwon Yongwoo, Hongik University, Korea Phase-field Modeling of Polycrystalline Microstructure Formation in Thin Films for Nanoelectronics	I2-28 Kim Tae Young, Seoul National University of Science and Technology, Korea Cooling Technologies for Microelectronics: A Focus on Nvidia GPU Tensor Core Cooling Solutions	
16:35-17:00	I2-13 Sanchez Debbie Claire, ERS electronic GmbH, Germany Yield Improvement in Advanced Packaging through New Photonic Wafer Debonding Technology	O2-05 Han Seungwoo, Korea Institute of Machinery and Materials (KIMM), Korea Thermal Fatigue Testing on Bonding Parts of Thermoelectric Devices using Peltier Effect	I2-19 Lee Myungho (Mike), TechL Co., Ltd., Korea Flexible PCB for mmWave Antenna Application	I2-24 Kuramochi Satoru, Dai Nippon Printing Co., Ltd., Japan Large Scale Glass substrate for High Performance Computing Application	O2-09 Choi Gwang-Mun, Electronics and Telecommunications Research Institute (ETRI), Korea Low-Carbon Epoxy-Siloxane Flux Technology for Fine-Pitch Solder Bump Interconnection	I2-29 Lee Hyungsoon, Chung-Ang University, Korea Embedded Liquid Cooling for High Performance Electronic Devices	
17:00-17:25	Banquet Setting		O2-06 Hladik Lukas, Tescan Group, A.S., Czech Streamlining Millimeter-Scale Semiconductor Failure Analysis: An Integrated Workflow with Plasma FIB-SEM, Laser Techniques, and Advanced FA Tools	I2-20 Kim Munho, Nanyang Technological University, Singapore Wafer Bonding and Single Crystal Nanomembrane for Flexible Electronics	General Meeting (Sydney)	O2-10 Joo Seung Hwan, Inha University, Korea Design and Performance Test of Newly Developed 10um Aerosol 3D Printing Nozzle Systems for EMI Shielding and Semiconductor Interconnect	I2-30 Chae-Yoon Kim, AnyCasting Co., Ltd., Korea Development of Electrochemical 3D Printing Technology for the Fabrication of Micro Bumps and Cooling Structures
17:25-18:00	Break Time						
18:00-20:00	Banquet and Haedong Award Ceremony (Grand Ballroom)						

Nov 8th, 2024 (Fri.)

Room	Grand Ballroom A (200)	Grand Ballroom B (100)	Capri (120)	Sicily (100)	Sydney (70)	Venice (32)	Miami (32)
Topic	Young Scientist II	Young Scientist III	Young Scientist IV		Special Session 5: Process, Material, Reliability and Simulation for RDL Packaging Technology	Special Session 6 (Closed Session)	Special Session 7 (Closed Session)
Session Chair	Oh Seung Jin	Kang Tae Yeob	Park Ah-Young		Choi Changhwan	Jung Ye Hwan	Sohn Yoonchul
9:00-9:15	O3-01 Jeong Inhye, Gwangju Institute of Science and Technology (GIST), Korea Effective Heat Dissipation in Three-Dimensional Integration with Crystalline Inter-bonding Dielectrics	O3-06 Choi Donggyu, Korea Institute of Industrial Technology (KITECH), Korea Enhancing Ultrafine Printability of Water-soluble Flux with Type 7 Solder Paste for Flip Chip Interconnects	O3-11 Youn Hayoung, Korea Institute of Machinery and Materials (KIMM), Korea Femtosecond Laser-Assisted SiC Wafer Thinning Process		S05-01 Kwan Kyu Park, Hanyang University, Korea Measurement of Electric Properties of PID (Photo-imageable dielectric) Film-based Test Structure		
9:15-9:30	O3-02 Kim Injoo, Seoul National University of Science and Technology, Korea The Strength of Dielectric Bond in Hybrid Bonding using Different Plasma Treatment Gases	O3-07 Jeong Daeyoon, Andong National University, Korea Effects of Annealing Conditions on the Interfacial Characteristics of ALD Ru/ZnO Thin Films for Advanced Interconnects	O3-12 Lee Yurim, Yonsei University, Korea Hydrogel-based Adhesive Film for Soft Electronics Packaging		S05-02 Changhwan Choi, Hanyang University, Korea Improved Adhesion between PSPI and Metal Layer for RDL Process		
9:30-9:45	O3-03 Kwon Yongbeom, Andong National University, Korea Post-bond Annealing Effect on the Quantitative Interfacial Adhesion Energy of Cu/Cu Interface for Low-temperature Hybrid Bonding	O3-08 Lee Min Geun, Korea Advanced Institute of Science and Technology (KAIST), Korea Thermal Conductivity Enhancement of Underfill Material with Inducing Double Percolation Effect from Core-shell Structure	O3-13 Yoo Woong-Kyoo, Hanyang University, Korea Automatic Pattern Classification-based Prediction of Warpage in Complex Patterned Semiconductor Packages Considering The Anisotropic Viscoelastic Properties		S05-03 Hongyun So, Hanyang University, Korea Analysis of Electrodeposition Process for Cu Microstructure	"Conductive Adhesive Materials for 3D Packaging" Hanyang University Sungkyunkwan University STECO	"Training of Semiconductor Advanced Packaging Specialists" Chosun University Chonnam National University Gwangju Institute of Science and Technology Inha University
9:45-10:00	O3-04 Ju Min Sang, Korea Advanced Institute of Science and Technology (KAIST), Korea Warpage and Delamination Behavior on Sub-100 μm Thickness Epoxy Molding Compound : An Investigation for Molded Underfill in Advanced 3D Packaging	O3-09 Yu Hayoung, Korea Institute of Industrial Technology (KITECH), Korea Microscale-tensile and Work Hardening Behaviors of Each Weld Part of Solid-state Cu to Cu Direct Bonding using Refill Friction Stir Spot Joining	O3-14 Ham Yeong Seok, Korea Advanced Institute of Science and Technology (KAIST), Korea Mechanical Reliability of SiCN - SiOC:H in BEOL Interconnects According to Fracture Mode		S05-04 Dong Rip Kim, Hanyang University, Korea Transient Thermal Analysis of Multi-layer RDL for 2.1D Package		
10:00-10:15	O3-05 Lee Gaeun, Electronics and Telecommunications Research Institute (ETRI), Korea Enhancing Reliability of 30μm-Pitch Micro-Bumps Using Room Temperature Laser-Assisted Bonding (LAB) with Laser Non-Conductive Paste (NCP)	O3-10 Shin Joochan, Sungkyunkwan University, Korea Polymeric Conductive Adhesive-Based Ultrathin Epidermal Electrodes for Long-Term Monitoring of Electrophysiological Signals	O3-15 Kim Beomgi, Andong National University, Korea In-situ Study on the Stress-temperature Characteristics of Cu/PI Thin Films for Heterogeneous Integration Packaging with Si-bridge		S05-05 Jaemyung Lim, Hanyang University, Korea The Study on Crosstalk for the Silicon Interposer		
10:15-10:30	Break Time				S05-06 Hak-Sung Kim, Hanyang University, Korea Experimental and Simulation Study for Accurate Warpage Prediction of Semiconductor Package		
Topic	Young Scientist V	Young Scientist VI	Young Scientist VII		Special Session 8 (Closed Session)	Special Session 9 (Closed Session)	Special Session 10: SimCrunch's Day (Closed Session)
Session Chair	Choe Seunghoe	Lee Yong-Seok	Kwon Jirmin		Yoo Sehoon	Kim Taek-Soo	Kim Sung Yong
10:30-10:45	O3-16 Kim Uhyeon, Pohang University of Science and Technology (POSTECH), Korea In-Situ Bonding of Ultra-Thin-Silicon Interposer via Transfer Printing for High Density Heterogeneous Integration	O3-21 Kim Young Gil, Sungkyunkwan University, Korea Thermally Managed, Injectable Optoelectronic Probe with Heat Dissipation Guide for Photodynamic Therapy	O3-26 Cho Donghyeon, Korea Advanced Institute of Science and Technology (KAIST), Korea Fabrication of an Ultra-Thin Fiber-Type Sensor for Deformation Measurement During Underfill Curing Process				
10:45-11:00	O3-17 Kim Taekhyeon, Hanyang University, Korea Reliability Improvement of RDL Interposer in Semiconductor Packages through Optimization of Electroplating Current Density	O3-22 Cho Hyunho, Korea Advanced Institute of Science and Technology (KAIST), Korea Jet Nozzle Array Optimization for Enhancing Temperature Uniformity in Direct Liquid Cooling of Semiconductor Packages with Non-uniform Heat Fluxes	O3-27 Ye Yeong-Sinn, Sungkyunkwan University, Korea Choline-based Ionic Liquids and Gels for Long Term Organic Electrochemical Transistors				
11:00-11:15	O3-18 Choi Hyesu, Sungkyunkwan University, Korea Highly Stretchable and Strain-Insensitive Liquid-Metal based Elastic Kirigami Electrodes (LM-eKE)	O3-23 Kim Minjin, Andong National University, Korea ALD ZnO barrier Effects on the Interfacial Adhesion Energy for Advanced ALD Ru Interconnects	O3-28 Jo Eunjin, Korea Institute of Industrial Technology (KITECH), Korea Oxidation-free Bonding of Ag Nanoporous Sheets onto Bare Cu Substrates for Improved EMC Molding Qualities		"Surface Finish Technology for Ultrafine Pitch Package Interconnect" Korea Institute of Industrial Technology (KITECH)	"High-reliability Silicon Bridge Heterogeneous Packaging Technology for High-efficiency Power Distribution" Korea Advanced Institute of Science and Technology (KAIST)	"Engineering Simulation-based Solution for Small and Medium-sized Business Difficulties" Tech University of Korea
11:15-11:30	O3-19 Sim Gyumin, Korea Advanced Institute of Science and Technology (KAIST), Korea Investigating Infiltration Time and Void Formation in Nanofiller-Based Underfill Materials for Semiconductor Applications	O3-24 Kim Heui-Su, Hanyang University, Korea Laser Spallation Test for Measurement of the Interfacial Adhesion of LPCVD and PECVD Silicon Nitride/Copper Films	O3-29 Kim Yehri, Korea Institute of Industrial Technology (KITECH), Korea Mechanical Performance of Oxygen-free Cu Sintering in the Air on Cold-rolled Cu Substrates				
11:30-11:45	O3-20 Lee Se Min, Hanyang University, Korea Enhancing Adhesion of Ti/Cu Seed Layers on ABF Substrate through Plasma Treatment and Seed Layer Thickness Variation	O3-25 Kim Younghoon, Inha University, Korea Study on the Electromagnetic Shielding Properties of External Copper Trace Design by Layer for MLP (Multi-layer PCB)	O3-30 Kim Sang-Il, Hanyang University, Korea In-situ Non-destructive Inspection Technique for Analyzing Chip Alignment and Warpage in Semiconductor Packages using Terahertz Waves				
11:45-12:00	Break Time						
12:00-12:20	ISMP Award Ceremony, Lucky Draw and Closing Remark (Grand Ballroom A)						